

SFT-20-RA

Projection LED



Features

- 2.0 mm² LED emitting area
- Drive current up to 8 A
- Standard 3535 SMT package
- Low thermal resistance $R_{th Junction to Case} = 1.03$ °C/W
- Dominant wavelength: Red Amber 613nm
- · Flat surface emission for high collection efficiency





Applications

- Entertainment / Stage Lighting
- · Medical / Life Science
- Industrial
- Transportation / Beacons
- High performance illumination

 Specifically engineered for stand alone, embedded, or battery-assisted projection display applications

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Ordering Information

Ordering Part Numbers¹

| 0-1 | Lumino | us Flux | \\\\\\\\\\\\\\\\\\\\\\\ | Ordering Part Number | |
|-------|---------------|-----------|-------------------------|----------------------|--|
| Color | Min. Flux Bin | Min. Flux | Wavelength bin | | |
| | 1A | 180 lm | R1, R2 | SFT-20-RA-F35-MPA | |
| RA | 1A | 180 lm | R1, R2 | SFT-20-RA-F35-MPA200 | |
| | 1B | 200 lm | R1, R2 | SFT-20-RA-F35-MPB200 | |

Part Number Nomenclature

SFT 20 RA ### <Bin kit>

| Product Family | Chip Area | Color | Package Configuration | Bin Kit |
|--------------------------------|-----------|---------------|--|---|
| SFT: Surface-Mount Flat-Top | 20: 2 mm² | RA: Red Amber | F35: 3535 EMC SMD R35: 3535 EMC mounted on Star-Board ² | Refer to ordering part numbers in this document |

^{1.} Flux Bin listed is minimum bin shipped, higher bins may be included at Luminus' discretion.

 $^{2. \,} Starboard \, Configuration \, R35 \, are \, available \, for \, small \, sample \, quantity \, only. \, For \, additional \, quantity, \, contact \, Luminus \, representative.$

Binning Structure

All SFT-20 LEDs are tested for luminous flux/ dominant wavelength and placed into one of the following flux/wavelength bins. The binning structure is universally applied across each monochromatic color of the SFT-20 product line.

Flux Bins^{1,2}

| Color | Luminous Flux Bin ³ | Binning @ 1.4 | 1 A, T _c = 25°C ⁴ |
|-----------|--------------------------------|-------------------|---|
| Color | Luminous Flux Bin | Minimum Flux (lm) | Maximum Flux (lm) |
| | 1A | 180 | 200 |
| Red Amber | 1B | 200 | 220 |
| | 1C | 220 | 240 |
| | 1D | 240 | 260 |
| | 1E | 260 | 285 |

Dominant Wavelength Bins²

| Color | Wayalangth Pin3.5 | Binning @ 1.4 | 4 A, T _c = 25°C ⁴ |
|------------|-------------------------------|-------------------------|---|
| COIOI | Wavelength Bin ^{3,5} | Minimum Wavelength (nm) | Maximum Wavelength (nm) |
| D. I.A. I. | R1 | 609 | 615 |
| Red Amber | R2 | 615 | 621 |

- 1. Luminus maintains a +/- 6% tolerance on flux measurements.
- 2. Products are production tested then sorted and packed by bin.
- 3. Individual bins are not orderable. Please refer to the Product Ordering information page for a list of orderable bin kits.
- 4. T_c = Case temperature.
- 5. The wavelength bin as marked on the product label may be followed by a letter which is for internal use only.

Absolute Maximum Ratings¹

| | Symbol | Values | Unit |
|---|---------------------|--------|------|
| Formulated Course of (Circulate value of 20 mag on Dullocal) 234 | I _{f min} | 0.4 | ٨ |
| Forward Current (Single pulse 20 ms or Pulsed) ^{2,3,4} | I _{f max} | 6.0 | A |
| Forward Current (Pulsed) ^{2,3,4} | I _{fp min} | 0.4 | |
| Frequency >240Hz, duty cycle <70% | l fp max | 8.0 | A |
| Forward Surge Current (Pulsed) ^{2,3,4} Frequency >240Hz, duty cycle <10%, t=1ms | l surge max | 9 | А |
| | T _{s min} | -40 | 20 |
| Storage Temperature | T _{s max} | 100 | °C |
| Junction Temperature ³ | T _{j max} | 110 | °C |
| ESD sensitivity ANSI/ESDA/JEDEC JS-001 (HBM, Class 2) | V _{ESD} | 2000 | V |

- 1. All ratings are based on standard testing conditions at drive current 1.4 A, 20ms single pulse at T_c = 25°C.
- $2. \ In pulsed operation, rise time from 10\% to 90\% of forward current should be larger than 0.5 microseconds.$
- 3. Product performance and lifetime data is specified at recommended forward drive current. Sustained operation at or near absolute minimum current may result in a reduction of device performance and device lifetime compared to recommended forward drive current.
- 4. Sustained operation above maximum current is not recommended and will result in a reduction of device lifetime.

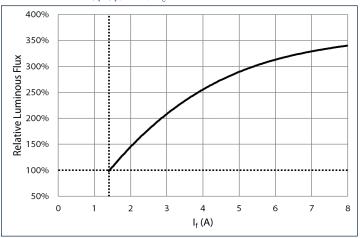
Device Characteristics¹

| Optical and Electrical Characteristics | Symbol | Value | Unit |
|---|----------------------------------|-------------|---------|
| Emitting Area | A_{E} | 2.0 | mm² |
| Emitting Area Dimension | | 1.31 x 1.55 | mm x mm |
| Reference Duty Cycle | | 100 | % |
| Test Peak Drive Current | l _f | 1.4 | А |
| Peak Luminous Flux ² | Φ_{V} | 250 | lm |
| Peak Radiometric Flux ² | Φ_{E} | 0.83 | W |
| | $V_{f min}$ | 2.0 | |
| Forward Voltage | V_{f} | 2.3 | V |
| | $V_{\mathrm{f}\ \mathrm{max}}$ | 3.0 | |
| | $\lambda_{	ext{d min}}$ | 609 | |
| Dominant Wavelength | $\lambda_{	ext{d typ}}$ | 613 | nm |
| | $\lambda_{	ext{d max}}$ | 621 | |
| Peak Wavelength | λ_{p} | 620 | nm |
| FWHM- Spectral bandwidth at 50% of $\Phi_{\rm V}$ | $\Delta\lambda_{_{1/2}}$ | 16 | nm |
| Observation Occupies to 22 | CIE x | 0.66 | |
| Chromaticity Coordinates ^{2,3} | CIE y | 0.32 | |
| Thermal Characteristics | | | |
| Electrical Thermal Resistance (junction to case) ^{4,5} | R _{th (j-c) electrical} | 1.03 | °C/W |
| Real Thermal Resistance (junction to case) ^{4,5} | R _{th (j-c) real} | 1.45 | °C/W |

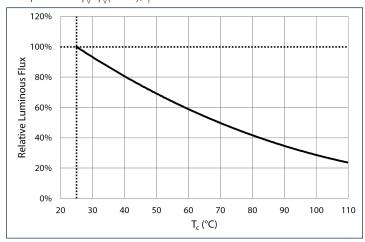
- 1. Product test condition: 1.4 A, 25°C case temperature.
- 2. Typical flux at typical dominant wavelength.
- 3. In CIE 1931 chromaticity diagram coordinates, normalized to X+Y+Z=1.
- 4. Thermal resistance values are based on modeled results correlated to measured $R_{th(j-c)}$ data using Forward Voltage sensitivity parametric method, compliant with JEDEC Standards JESD51-14.
- 5. For optimal results, Luminus recommends customer PCB Design per guidelines from Luminus application note, "Design Guidelines for SFT Chipset Assembly".

Relative Luminous Flux

Forward current: $\phi_v/\phi_v(1.4 \text{ A})$, $T_c = 25^{\circ}\text{C}$

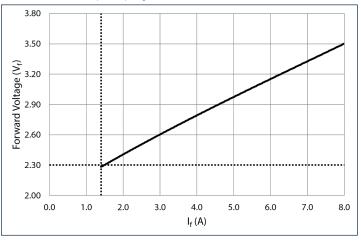


Temperature: $\varphi_v/\varphi_v(25^{\circ}C)$, $I_f = 1.4 \text{ A}$

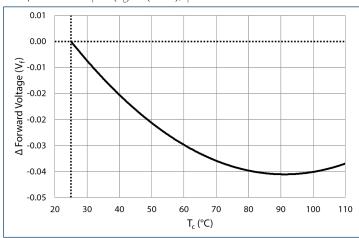


Forward Voltage

Forward current: $V_f = V(I_f)$, $T_c = 25$ °C

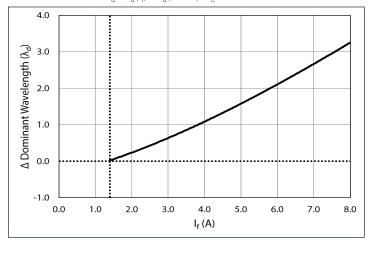


Temperature: $\Delta V_f = V(T_c) - V(25^{\circ}C)$, $I_f = 1.4 A$

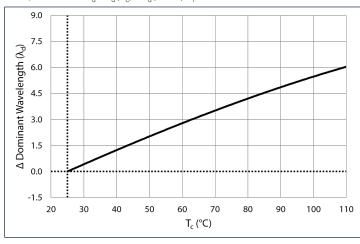


Dominant Wavelength Shift

Forward current: $\Delta \lambda_d = \lambda_d(I_f) - \lambda_d(1.4 \text{ A})$, $T_c = 25^{\circ}\text{C}$



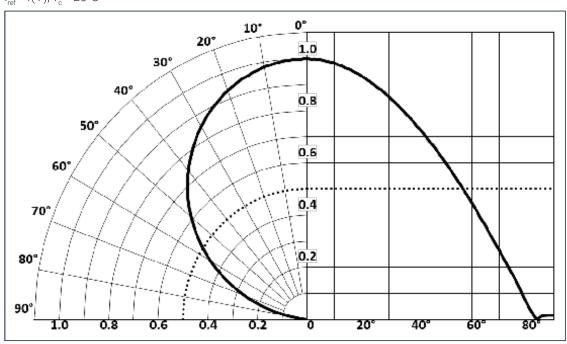
Temperature: $\Delta \lambda_d = \lambda_d (T_c) - \lambda_d (25^{\circ}C)$, I_f = 1.4 A



Angular Distribution and Typical Spectrum

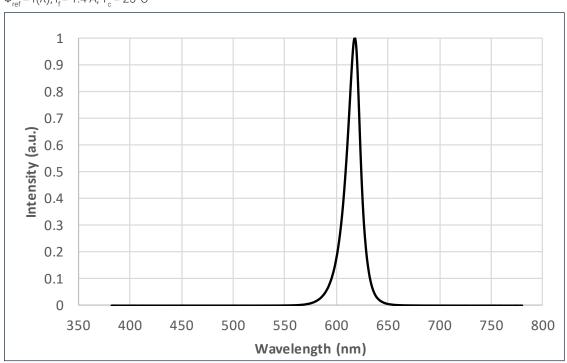
Angular Intensity Distribution

 $I_{ref} = f(\Phi); T_{c} = 25^{\circ}C$

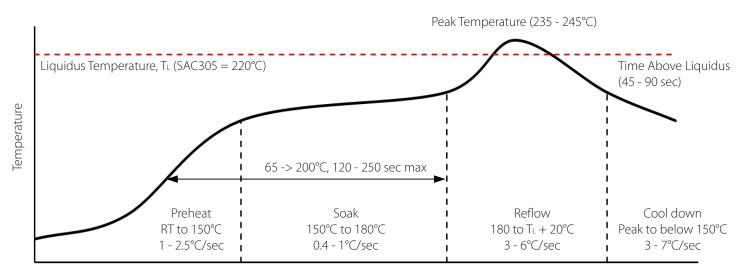


Typical Spectrum

$$\Phi_{ref} = f(\lambda); I_f = 1.4 \text{ A}; T_c = 25^{\circ}\text{C}$$



Soldering Profile



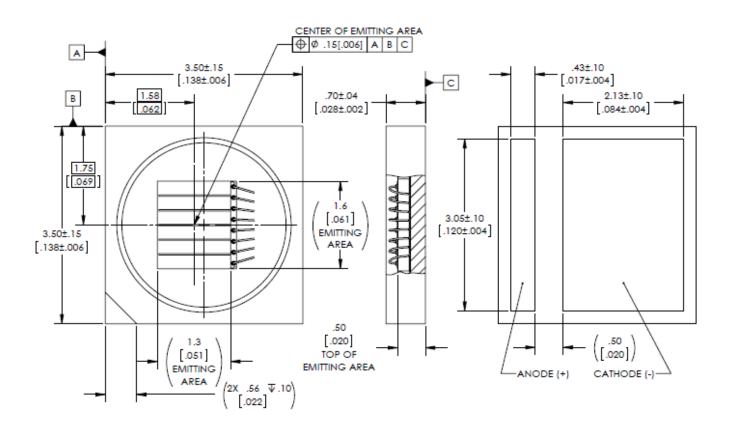
Time

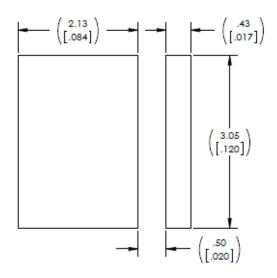
| SMT Rework Guideline | Manual Hotplate Reflow Hot Air Gun Reflow | | |
|----------------------|---|--|--|
| Heating Time | < 60 sec | | |
| Hotplate Temperature | < 245°C < 150°C | | |

- 1. Product complies to Moisture Sensitivity Level 3 (MSL 3).
- 2. The numbers in the table are specific to SAC305. Luminus recommends using an SAC305 solder paste with a no-clean flux for RoHS compliant products.
- 3. During the pick and place process, ensure the pick-up tool does not touch any die components.
- ${\bf 4.}\ Use of a multi-zone\ IR\ reflow\ oven\ with\ a\ nitrogen\ blanket\ is\ recommended.$
- 5. Time-temperature profile of the reflow process showing the four functional profile zones are defined in IPC-7801. Temperature is referenced to the center of the PCR
- $6. \ Luminus\ recommends\ to\ use\ the\ solder\ paste\ data\ sheet\ information\ as\ a\ starting\ point\ in\ time-temperature\ process\ development.$
- 7. These are general guidelines. Consult the solder paste manufacturer's datasheet for guidelines specific to the alloy and flux combination used in your application.

 For more information, please refer to:
 - $\underline{https://luminusdevices.zendesk.com/hc/en-us/articles/360060306692-How-do-l-Reflow-Solder-Luminus-SMD-Components-luminus-SMD-Component$
- 8. For any technical questions about soldering process, please contact Luminus at techsupport@luminus.com.

Mechanical Dimensions

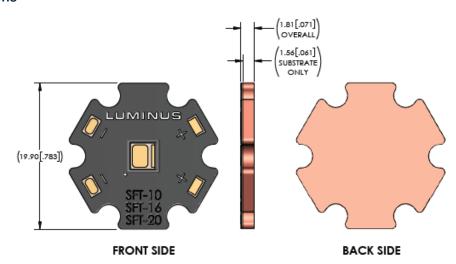


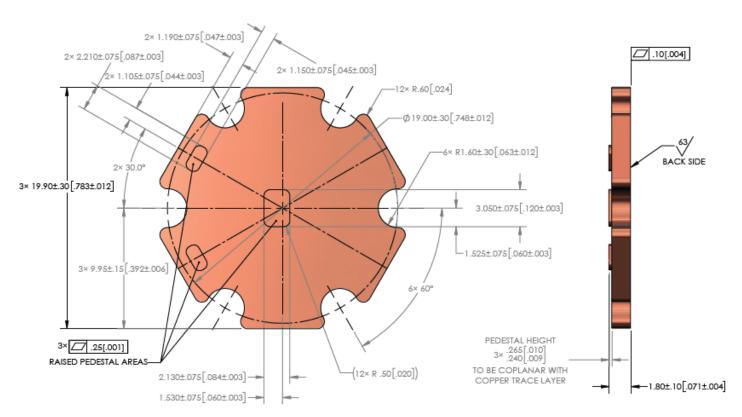


RECOMMENDED SOLDER PAD LAYOUT

Mechanical Dimensions

Starboard dimensions

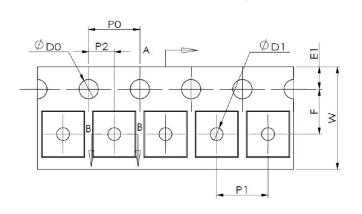


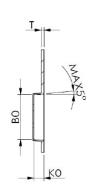


BASE WITH RAISED PEDESTAL AREAS

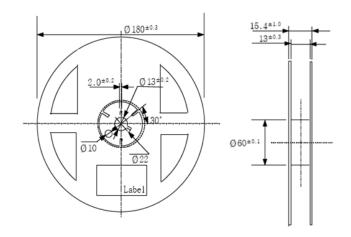
Tape and Reel Outline

Shipping Reel Outline

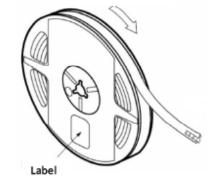




| Parameter | Dimension (mm) |
|-----------|----------------|
| В0 | 4.00 +/- 0.10 |
| K0 | 1.20 +/- 0.10 |
| P0 | 4.00 +/- 0.10 |
| P1 | 8.00 +/- 0.10 |
| P2 | 2.00 +/- 0.05 |
| Т | 0.30 +/- 0.05 |
| E1 | 1.75 +/- 0.10 |
| F | 5.50 +/- 0.05 |
| D0 | 1.55 +/- 0.05 |
| D1 | 1.55 +/- 0.05 |
| W | 12.00 +/- 0.10 |



User Feed Direction

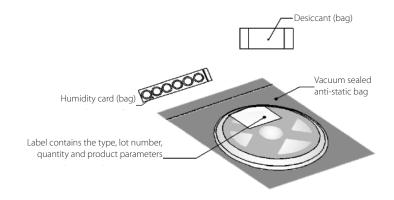


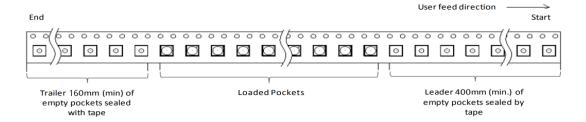
| Parameter | Quantity (pcs) |
|-----------------|----------------|
| D: . | 250 |
| Pieces per reel | 500 |

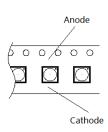
- 1. The quantity per reel is not orderable.
- 2. Minimum order quantity: 500 pcs.

Tape and Reel Outline

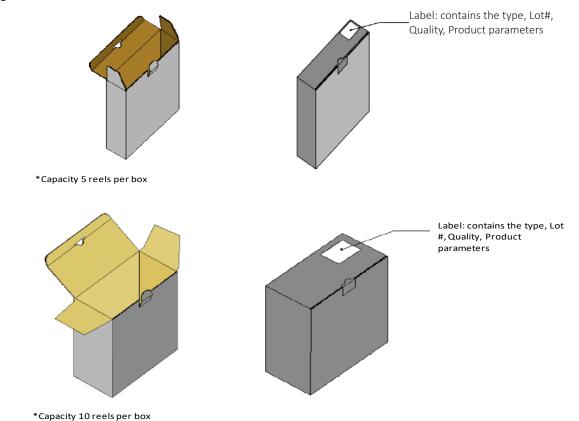
Reel Package



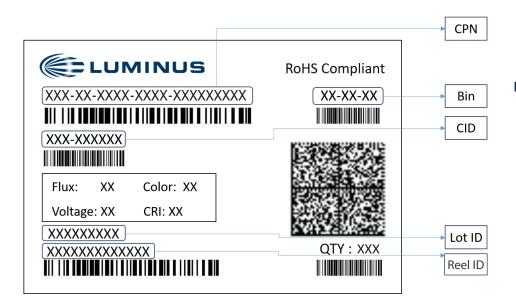




Box Packaging Information



Shipping Label



Label Fields:

- CPN: Luminus ordering part number
- CID: Customer's part number
- QTY: Quantity of devices in pack
- Flux: Bin as defined on page 3
- Voltage: NA
- Color: Bin as defined on page 3
- CRI: NA

Packing Configuration:

- Maximum of 500 devices per reel
- Partial reel may be shipped
- Each pack is enclosed in anti-static bag
- · Shipping label is placed on top of each pack

Notes

Static Electricity

This product is sensitive to static electricity, and care should be taken when handling them. Static electricity or surge voltage will damage the LEDs. It is recommended to wear an anti-electrostatic wristband or anti-electrostatic gloves when handling the LEDs. All devices, equipment and machinery must be properly grounded. It is recommended that measures be taken to isolate LED processing equipment from potential sources of voltage surges.

Reference: APN-002815 Electrical Stress Damage to LEDs and How to Prevent It

Eye Safety

According to the test specification risk group IEC 62471: 2006-Non-GLS under 1.4 A, this product complies to Risk group 0 (RG0) Exempt.

No photo biological hazard under foreseeable conditions.

For more information, please refer to: https://luminusdevices.zendesk.com/hc/en-us/articles/10532958752397

Revision History

| Rev | Date | Description of Change |
|-----|------------|---|
| 01 | 12/13/2023 | Initial release as single color SFT-20. Replacing SFT-20 RGB datasheet PDS-002824 |